

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property
Organization
International Bureau



(43) International Publication Date
28 April 2005 (28.04.2005)

PCT

(10) International Publication Number
WO 2005/037488 A1

(51) International Patent Classification⁷: **B24B 37/04**

(21) International Application Number:
PCT/JP2004/015566

(22) International Filing Date: 14 October 2004 (14.10.2004)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
2003-358593 17 October 2003 (17.10.2003) JP

(71) Applicant (for all designated States except US): **EBARA CORPORATION** [JP/JP]; 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo 144-8510 (JP).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **TORII, Hiroomi** [JP/JP]; c/o Ebara Corporation, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo 144-8510 (JP). **HAYAMA, Takuji** [JP/JP]; c/o Ebara Corporation, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo 144-8510 (JP). **YASHIMA, Tetsuya** [JP/JP]; c/o Ebara Corporation, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo 144-8510 (JP).

(74) Agents: **WATANABE, Isamu** et al.; GOWA Nishi-Shinjuku 4F, 5-8, Nishi-Shinjuku 7-chome, Shinjuku-ku, Tokyo 160-0023 (JP).

(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

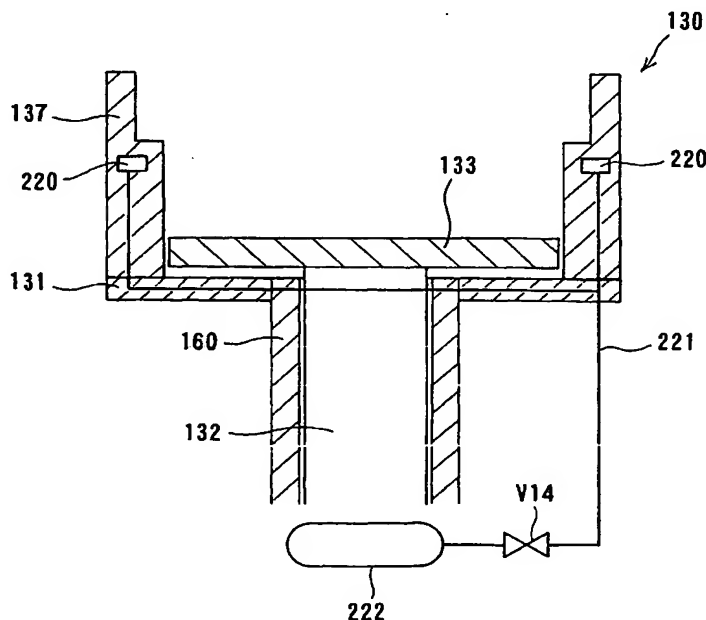
(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

— with international search report

[Continued on next page]

(54) Title: **POLISHING APPARATUS**



(57) Abstract: A polishing apparatus has a top ring (1) configured to hold a semiconductor wafer (W) on a substrate holding surface and a pusher (130) configured to deliver the semiconductor wafer (W) to the top ring (1) and receive the semiconductor wafer (W) from the top ring (1). The pusher (130) includes a push stage (133) having a substrate placement surface on which the semiconductor wafer (W) is placed and an air cylinder (135) configured to vertically move the push stage (133). The pusher (130) also includes a high-pressure fluid port (220) configured to eject a high-pressure fluid toward the semiconductor wafer (W).

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